



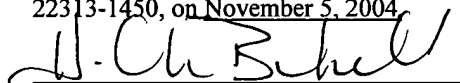
IFW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<i>In Re</i> Application of:)	
)	
Shen, et al)	Group Art Unit: 2811
)	
Serial No.: 10/668,985)	Examiner: Vu, Quang D.
)	
Filed: September 22, 2003)	Confirmation Number: 1771
)	
For: Pad Structure of Semiconductor)	TKHR Docket No.: 251310-1090
Device for Reducing or Inhibiting)	Sundial Ref.: US1260PA
Wire Bonding Cracks)	
)	

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postage prepaid, in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 5, 2004.


Signature – Hui Chin Barnhill

RESPONSE TO ELECTION OF SPECIES

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The Office Action mailed October 5, 2004, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.